

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV

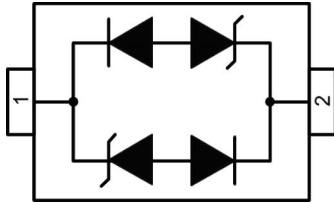


GDT



PLED

Product data sheet



SOD-323

Features

- ◆ 350W peak pulse power (8/20 μ s)
- ◆ Ultra low capacitance : 1.0pF typical
- ◆ Ultra low leakage: nA level
- ◆ Low Operating: 8V
- ◆ Low clamping voltage
- ◆ Protects one power line or data line
- ◆ Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: \pm 30kV
Contact discharge: \pm 30kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)
- ◆ RoHS Compliant

Mechanical Characteristics

- ◆ Package: SOD-323
- ◆ Lead Finish: Matte Tin
- ◆ Case Material: "Green" Molding Compound.
- ◆ UL Flammability Classification Rating 94V-0
- ◆ Moisture Sensitivity: Level 3 per J-STD-020
- ◆ Terminal Connections: See Diagram Below
- ◆ Marking Information: See Below

Applications

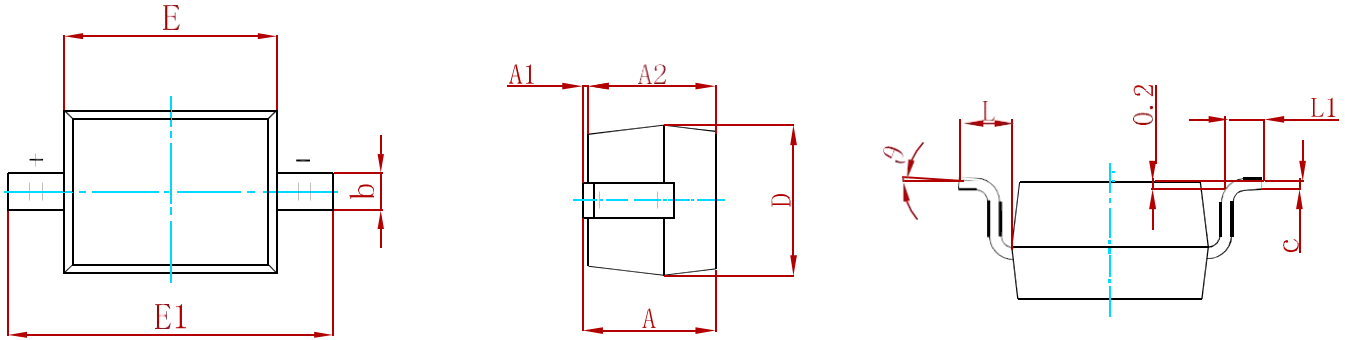
- ◆ USB Ports
- ◆ Smart Phones
- ◆ Wireless Systems
- ◆ Ethernet 10/100/1000 Base T

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air)	V _{ESD}	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	T _J	-40 to +85	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

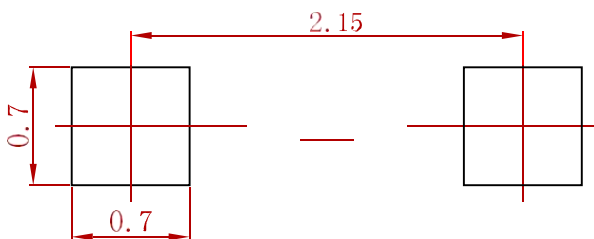
GBLC08CI-MS						
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V _{RWM}			8	V	
Breakdown Voltage	V _{BR}	8.5			V	I _T = 1mA
Reverse Leakage Current	I _R		1	100	nA	V _{RWM} = 8V
Clamping Voltage	V _C			14	V	I _{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	V _C			19	V	I _{PP} = 13A (8 x 20μs pulse)
Peak Pulse Current	I _{PP}			13	A	t _p =8/20μs
Junction Capacitance	C _J		1		pF	V _R = 0V, f = 1MHz

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
GBLC08CI-MS	SOD-323	3000

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